IPC ASSOCIATION CON ELECTRONICS INC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhtp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi				als and Mf	g Informati	ion		
upplier In	nformation													
Company name*				Company unique ID			Unique ID Authority				Response Date*			
nsemi										2023-06-08				
Contact Name	e	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-	-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Re	epresentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	re Date Version Manufacturing Site		Manufacturing Site	W	eight*	UOM	Unit Type
	MB6S BR		BR SOIC4 GPPN 0.5A 600V			2023-06-08		P	PANJITFG		21.031	mg	Each	
	rring Process Information Process Information		Corminal Daga	Alloy	STD-020 MSL	Poting	Dook Prog	ogg Pody To	mporatur	May Time at Peak	Tomporotu	ra Numb	per of Reflow Cyc	Jac
1 2 1		Terminal Base Alloy J-STD-020 CU Alloy 1		21D-070 M2F	Kanng	Peak Process Body Tempera 260 C		mperatur				ber of Kellow Cyc	ies	
•	itte 1111 (Sn) - annealed	Į.	O Alloy	1			200		<u> C</u>	30	second	s 3		
omments		·		20 1-										
	mum time at peak tempera													
r more info	ormation regarding materia	d composition	piease refer to	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itaability and the Company's remedies for issues that arise regarding information the Supplier provides in this f										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.276	mg	A	Lead (Pb)	7439-92-1	7c	0.2052	mg
			Supplier	Silicon (Si)	7440-21-3		4.0109	mg
			В	Nickel (Ni)	7440-02-0		0.0385	mg
			Supplier	Gold (Au)	7440-57-5		0.0214	mg
Die Attach Solder	3.313	mg	Supplier	Silver (Ag)	7440-22-4		0.0828	mg
			A	Lead (Pb)	7439-92-1	7a	3.0645	mg
			Supplier	Tin (Sn)	7440-31-5		0.1656	mg
Lead Frame	40.008	mg	Supplier	Iron (Fe)	7439-89-6		0.048	mg
			Supplier	Copper (Cu)	7440-50-8		39.948	mg
			Supplier	Phosphorus (P)	7723-14-0		0.012	mg
Mold Compound-Black	72.824	mg		Metal Hydroxide	proprietary data		2.5488	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		5.8259	mg
			Supplier	Carbon Black (C)	1333-86-4		0.3641	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		58.2592	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		5.8259	mg
Plating	0.61	mg	Supplier	Tin (Sn)	7440-31-5		0.61	mg